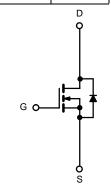


NCE40H12K-VB Datasheet N-Channel 40-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^{a, c}	Q _g (Typ.)			
40	0.0016 at V _{GS} = 10 V	120	120 nC			
40	0.0020 at V _{GS} = 4.5 V	100	120110			

TO-252

G D S



FEATURES

- Trench Power MOSFET
- 100 % R_g and UIS Tested



APPLICATIONS

- Synchronous Rectification
- Power Supplies

N-Channel	MOSFET
IN-CHAINE	MOSI LI

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	40	V		
Gate-Source Voltage		V_{GS}		± 25	
	T _C = 25 °C		120 ^{a, c}		
Continuous Drain Current /T 475 °C	T _C = 70 °C		96 ^c		
Continuous Drain Current (T _J = 175 °C)	T _A = 25 °C	I _D	29 ^b	^	
	T _A = 70 °C		23 ^b	A	
Pulsed Drain Current	I _{DM}	250			
Avalanche Current Pulse		I _{AS}	96		
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	320	mJ	
Continuous Course Durin Binds Courset	T _C = 25 °C	1	120 ^{a, c}	A	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	2.6 ^b		
	T _C = 25 °C		312 ^a		
Manifestor Brown Black of the	T _C = 70 °C		200	14/	
Maximum Power Dissipation	T _A = 25 °C	P _D	3.13 ^b	W	
	T _A = 70 °C		2.0 ^b		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^b	Steady State	R _{thJA}	32	40	°C/W		
Maximum Junction-to-Case	Steady State	R_{thJC}	0.33	0.4	C/VV		

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. Calculated based on maximum junction temperature. Package limitation current is 120 $\,\mathrm{A.}$



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	40			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		41		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1D = 200 μΛ		- 8			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2		2.5	V	
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zoro Coto Voltago Drain Current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V			1	^	
Zero Gate Voltage Drain Current		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
David Course Co. Otata Basista and	D	V _{GS} = 10 V, I _D = 30 A		0.0016		0	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		0.0020		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 30 A		180		S	
Dynamic ^b				•			
Input Capacitance	C _{iss}			9000		pF	
Output Capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		650			
Reverse Transfer Capacitance	C _{rss}			450			
Total Gate Charge	Q_{g}			120	180	nC	
Gate-Source Charge	Q_{gs}	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		30			
Gate-Drain Charge	Q _{gd}			16			
Gate Resistance	R_{g}	f = 1 MHz		0.85	1.3	Ω	
Turn-On Delay Time	t _{d(on)}			20	30		
Rise Time	t _r	V_{DD} = 20 V, R_L = 1.0 Ω		11	17	ns	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 20 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		77	115		
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			102	155		
Rise Time	t _r	V_{DD} = 20 V, R_L = 1.0 Ω		62	95		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 20 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		180	270		
Fall Time	t _f			60	90		
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			110	^	
Pulse Diode Forward Current ^a	I _{SM}				200	Α	
Body Diode Voltage	V _{SD}	I _S = 20 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			50	75	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 00 A di/dt 400 A/v- T 05 00		70	105	nC	
Reverse Recovery Fall Time	t _a	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		30			
Reverse Recovery Rise Time	t _b			20		ns	

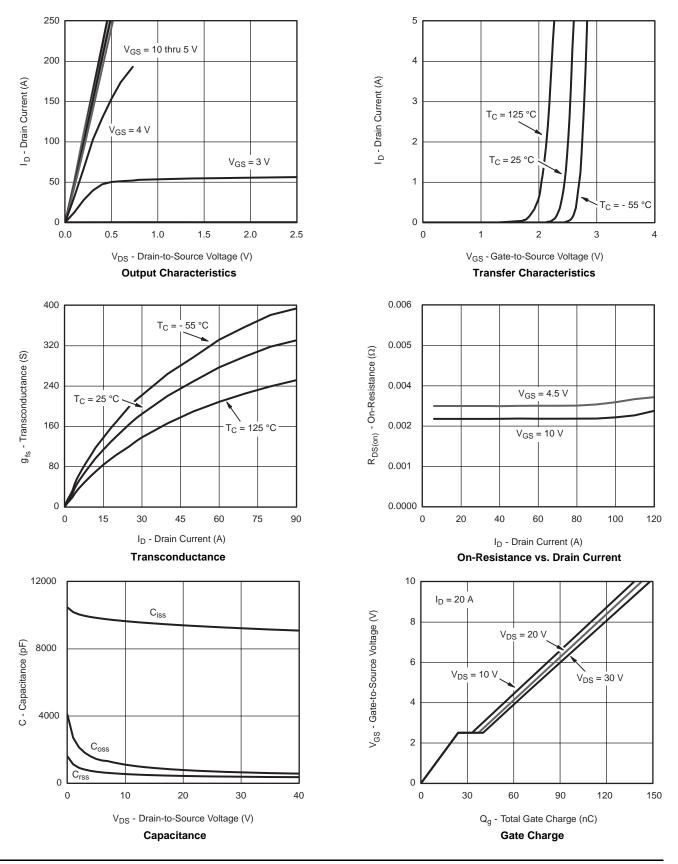
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

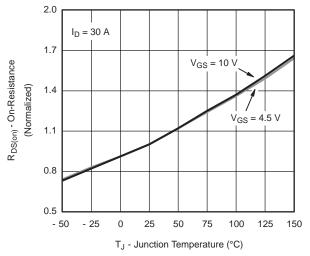


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

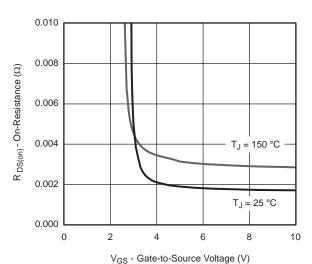




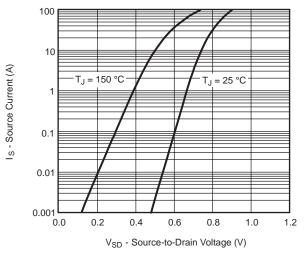
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



On-Resistance vs. Junction Temperature



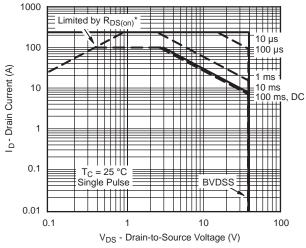
On-Resistance vs. Gate-to-Source Voltage



Forward Diode Voltage vs. Temperature



Threshold Voltage

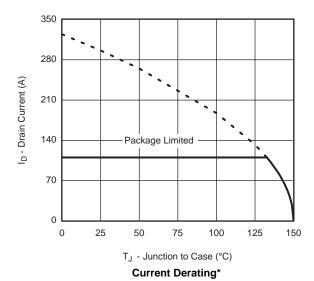


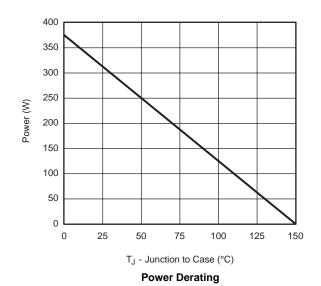
 * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





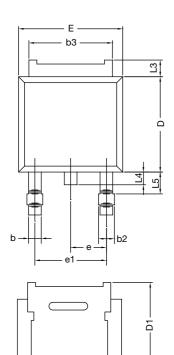
* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

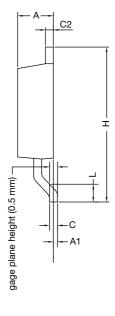


Normalized Thermal Transient Impedance, Junction-to-Case



TO-252AA CASE OUTLINE





	MILLIMETERS		ETERS INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28 BSC		0.090 BSC		
e1	4.56 BSC		0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12-0247-Rev. M, 24-Dec-12					

DWG: 5347

Note

• Dimension L3 is for reference only.



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